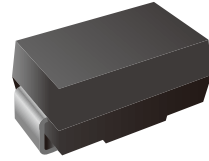


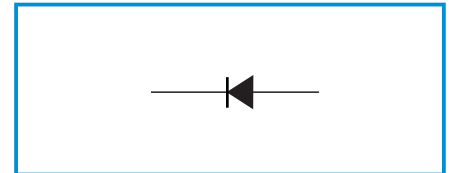
## Surface Mount General Rectifier



### Features

- Glass passivated chip junction
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed:  
260°C/10 seconds at terminals
- The plastic package carries Underwriters Laboratory  
Flammability Classification 94V-0

Functional Diagram



### Mechanical Data

- **Case:** JEDEC DO-214AC molded plastic body
- **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity:** Color band denotes cathode end
- **Mounting Position:** Any
- **Weight :** 0.002 ounce, 0.07 grams
- **Marking :** S2A~S2M

### Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.  
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

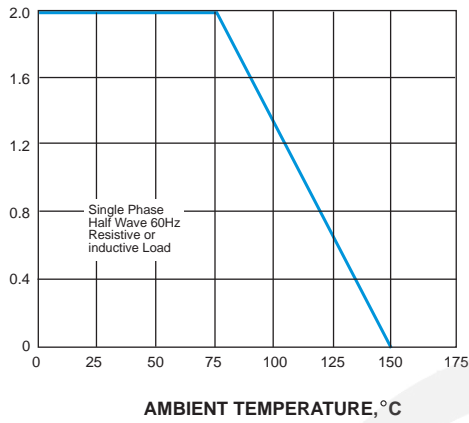
	SYMBOLS	LTS2A	LTS2B	LTS2D	LTS2G	LTS2J	LTS2K	LTS2M	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at $T_L=75^\circ\text{C}$	$I_{(AV)}$	2.0							Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	60.0							Amps
Maximum instantaneous forward voltage at 2.0A	$V_F$	1.1							Volts
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	$I_R$	5.0 50.0							$\mu\text{A}$
Typical junction capacitance (NOTE 1)	$C_J$	30.0							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	50.0							$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-65 to +150							$^\circ\text{C}$

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

## Ratings and characteristics Curves

AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

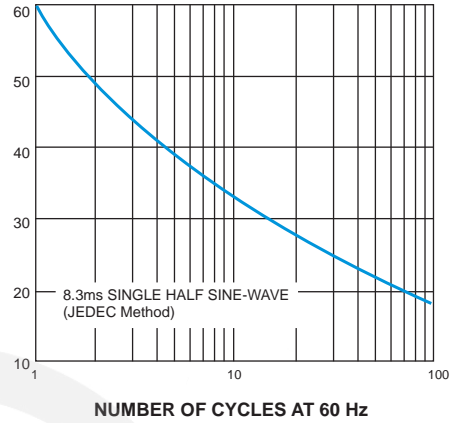


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

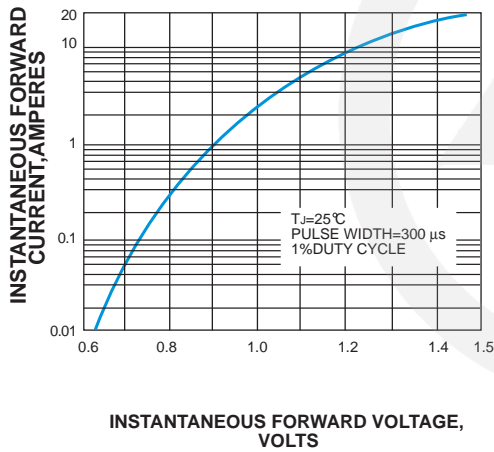


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

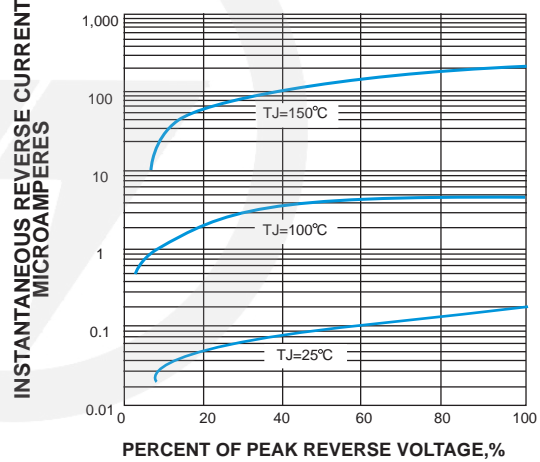
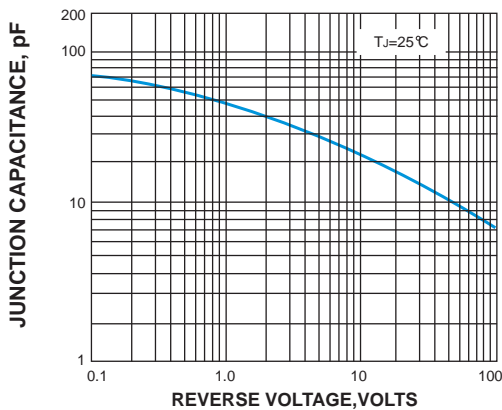
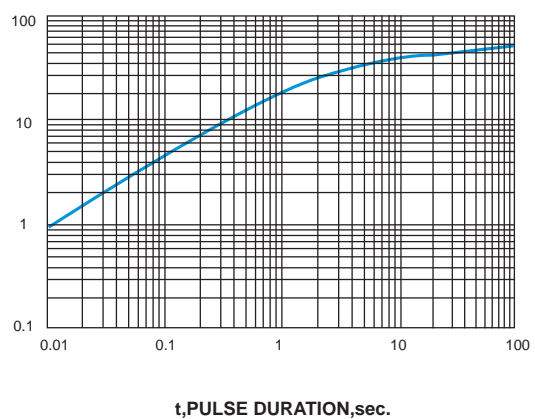


FIG. 5-TYPICAL JUNCTION CAPACITANCE

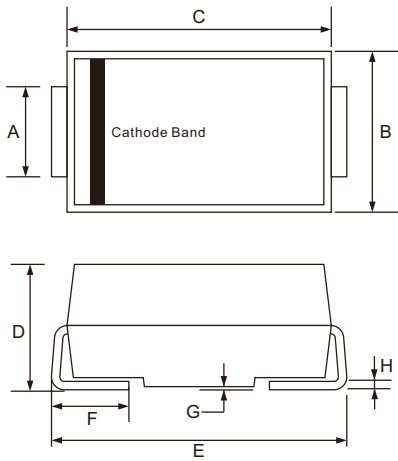


TRANSIENT THERMAL IMPEDANCE,  $^{\circ}\text{C}/\text{W}$

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



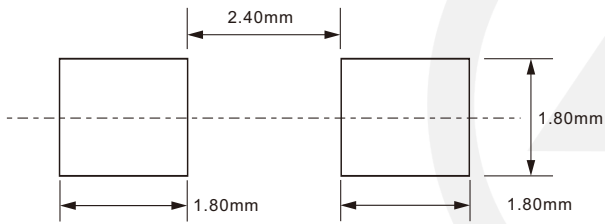
## SMA Package Outline



Unit : mm

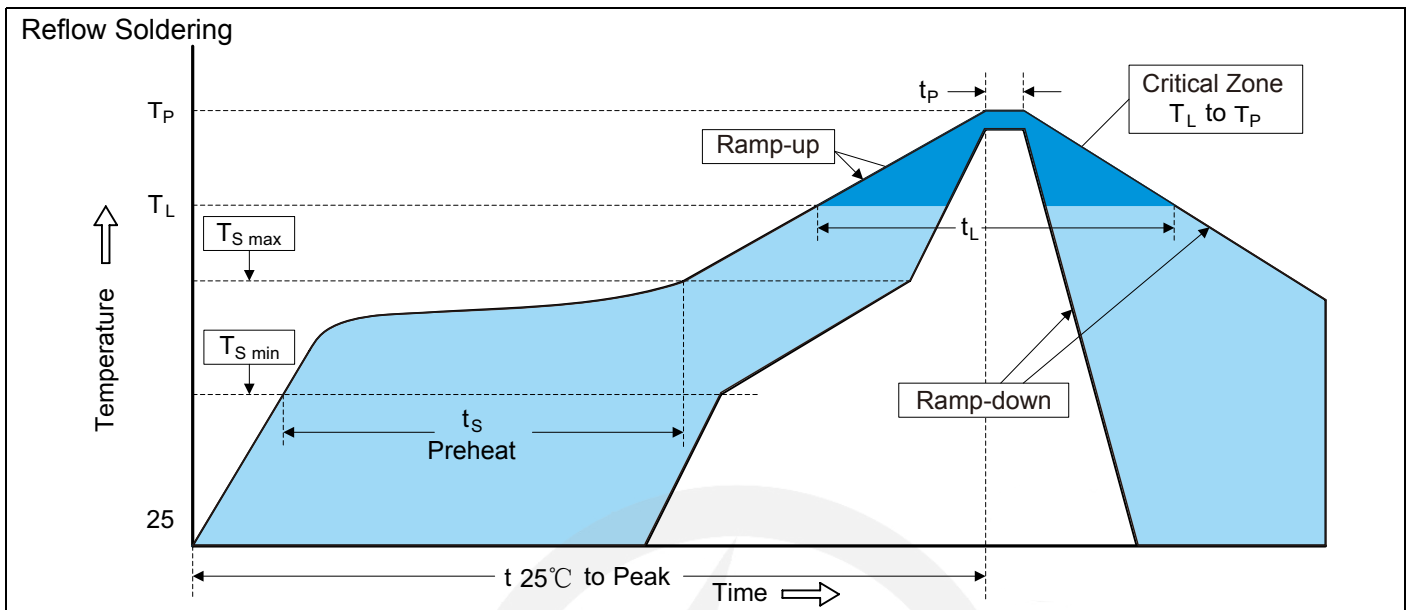
SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.25	1.65
B	2.30	2.79
C	4.00	4.75
D	1.90	2.50
E	4.70	5.28
F	0.76	1.52
G	0.203 TYP.	
H	0.15	0.31

## SMA Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$
3. The pad layout is for reference purpose only.

**Recommended Soldering Conditions**

**Recommended Conditions**

Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat -Temperature Min ( $T_{S\ min}$ ) -Temperature Max ( $T_{S\ max}$ ) -Time (min to max) ( $t_s$ )	150°C 200°C 60-180 seconds
$T_{S\ max}$ to $T_L$ -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature ( $T_L$ ) -Time ( $t_L$ )	217°C 60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_P$ )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

**Packaging**

13" Reel


 D5       $\Phi 330.0 \pm 2.0$ 

 D6       $\Phi 13.5 \pm 0.5$ 

 H       $2.5 \pm 1.0$ 

 W2       $16.0 \pm 2.0$ 

Quantity: 5000PCS